ABSTRACT OF THE DISCLOSURE

A semiconductor part fixing jig and a cradle according to the present invention are characterized in that a coating layer containing chromium oxide as chief ingredient thereof has been formed on a surface of a base metal. Furthermore, they are characterized in that the chromium oxide is chromium (III) oxide (Cr_2O_3). In addition, they are characterized in that the chromium oxide comprises fine chromium (III) oxide (Cr_2O_3) grains having an average grain diameter in the range of 0.1 to 0.5μm. A bonding device according to the present invention is formed by using the semiconductor part fixing jig and the cradle. By using the above described configuration, there is provided a semiconductor part fixing jig, a cradle, and a bonding device having high wear resistance, capable of reducing the generation and adhesion of dust caused by peeling off of the coating layer, and making possible the accurate recognition of the coordinate position of a lead or the like at the time of bonding operation.